

Texas Instruments Innovation Challenge: India Analog Design Contest 2014

Format – Letter of Intent

(Should be received on college letterhead by August 15 along with copy of project proposal)

To:
Dr. C.P. Ravikumar
Director, University Relations
Texas Instruments India
Bagmane Tech Park, CV Raman Nagar
Bangalore 560093
Phone - +91 80 2509 9727

Date:

Dear Dr. Ravikumar,

I am pleased to convey the interest of our institution <Name of the Institution> to enroll in the Texas Instruments Innovation Challenge: India Analog Design Contest 2014. Please confirm our enrollment. I am enclosing the details of the three (or more) teams from our institution.

Teams	Names of the Student Members	Course (B.E./B.TECH/ M.E./M.Tech/Ph.D) and Semester Information of students	Name of the Student Coordinator of each team	Name and Contact Details of Faculty Mentor(s)	Title of the Project
Team 1					
Team 2					
Team 3					

I hereby declare that the students members of the teams are bona-fide undergraduate/postgraduate students and the mentors are bona-fide faculty members of _____<<College Name and University Name>>_____ and will carry out the projects in our institution. We understand that the projects should not have been submitted to any other contest and will not be submitted to any other contest. Please confirm the enrollment of our institution in the contest. We will send the final submissions of the projects in due course.

Thanks and Regards,

Signature and seal of the Principal or HOD

Enclosures:
Project proposals

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